



LP-ISM050

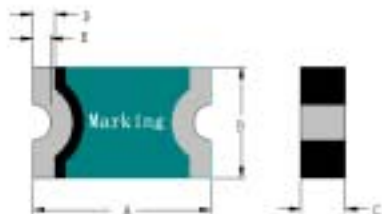
Features

- Very small size of 0805
- Fast tripping resettable circuit protection
- Surface mount packaging for automated assembly
- Agency recognition: UL、CSA、TUV



Product Dimensions (mm)

Part number	A	B	C	D	E
	Max	Max	Max	Max	Min.
LP-ISM050	2.20	1.50	1.25	0.10	0.20

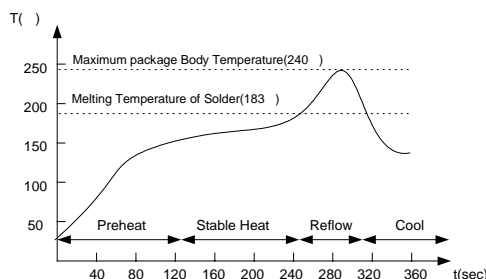
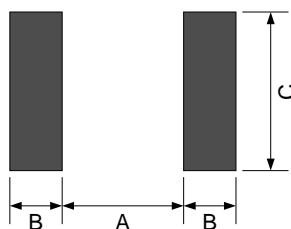


Electrical Characteristics

Part number	I _H (A)	I _T (A)	V _{max} (V)	I _{max} (A)	T _{trip} Current(A) Time(S)	P _{d typ} (W)	R _{min} ()	R _{1max} ()
LP-ISM050	0.50	1.00	6.00	40.0	8.00 0.10	0.5	0.15	0.85

I_H=Hold current: maximum current at which the device will not trip at 25 °C still air.
 I_T=Trip current: minimum current at which the device will always trip at 25 °C still air.
 V_{max}=Maximum voltage device can withstand without damage at rated current.
 I_{max}=Maximum fault current device can withstand without damage at rated voltage.
 T_{trip}=Maximum time to trip(s) at assigned current.
 R_{min}=Minimum device resistance at 25 °C prior to tripping.
 R_{1max}=Maximum device resistance measured in the nontripped state 1 hour post reflow.

Solder Reflow Recommendations



Solder Pad Layouts

Part number	A (mm)	B (mm)	C (mm)
LP-ISM050	1.80	1.00	1.80

* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

* Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.